CLAIM AMENDMENTS

1. (Cancelled)
2. (Cancelled)
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4. (Cancelled)
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14. (Cancelled)
15. (Cancelled)
16. (Cancelled)
17. (Cancelled)
18. (Cancelled)

19. (Currently Amended) In combination, an electrically conductive or semi-conductive surface and a current collector structure for collecting current from said electrically conductive or semi-conductive surface, said current collector structure comprising,

- a sheetlike substrate having a first substrate surface,

- a first material overlaying a portion of said first substrate surface, said first material comprising a polymer~~,~~ and further characterized as ~~having a first pattern,~~ being selectively positioned on said first substrate surface in a first trace pattern,

- an electrically conductive material coating said first trace pattern, ~~a second pattern comprising an electrodeposited metal, said second pattern being at least partially defined by said first pattern,~~ said electrically conductive material forming a second pattern characterized as substantially replicating said first pattern,

said combination characterized by having ~~said electrodeposited metal in electrical communication with said conductive or semi-conductive surface~~ at least a portion of said electrically conductive material positioned between said first material and said conductive or semi-conductive surface.

20. (Previously presented) The combination of claim 19 wherein said conductive or semi-conductive surface is a light incident surface of a photovoltaic cell.

21. (Previously presented) The combination of claim 20 wherein said photovoltaic cell comprises a thin film semiconductor structure.

22. (Previously presented) The combination of claim 21 wherein said thin film semiconductor structure is supported on a metal based foil.

23. (Cancelled)

24. (Cancelled)

25. (Cancelled)

26. (Currently amended) The combination of claim 19 wherein said first substrate surface comprises a polymeric adhesive.

27. (Currently amended) The combination of claim 26 wherein portions of said first substrate surface ~~is~~ are adhesively bonded in direct contact to said conductive or semi-conductive surface.

28. (Cancelled)

29. (Previously presented) The combination of claim 19 wherein said sheetlike substrate comprises silicon.

30. (Cancelled)

31. (Currently amended) The combination of claim 19 wherein said ~~electrodeposited metal~~ second pattern comprises multiple fingers ~~, said multiple fingers~~ joined by a buss, and wherein said second pattern is further characterized as comprising ~~multiple fingers and said buss are formed at least in part by~~ a monolithic ~~continuous electrodeposited~~ metal deposit extending to form ~~forming~~ portions of both said multiple fingers and said buss.

32. (Previously presented) The combination of claim 19 wherein said first material comprises printed material.

33. (Previously presented) The combination of claim 19 wherein said first material comprises a material component characterized as having the ability to assist deposition of metal.

34. (Previously presented) The combination of claim 33 wherein said material component is an electrically conductive polymer.

35. (Previously presented) The combination of claim 33 wherein said material component is a directly electroplateable resin (DER).

36. (Previously presented) The combination of claim 33 wherein said material component comprises a seed catalyst suitable for initiating chemical metal deposition.

37. (Currently amended) The combination of claim 19 wherein said ~~electrodeposited metal~~ electrically conductive material comprises ~~a Group VIII metal~~ an electroplated metal or metal-based alloy.

38. (Currently amended) The combination of claim ~~19~~ 37 wherein said ~~electrodeposited~~ electroplated metal or metal-based alloy comprises copper ~~a metal chosen from the group nickel, copper or silver~~ .

39. (Currently amended) The combination of claim 19 wherein said ~~second pattern~~ electrically conductive material comprises a low melting point metal based material.

40. (Currently amended) The combination of claim 39 wherein said ~~second pattern~~ electrically conductive material comprises indium.

41. (Currently amended) In combination, ~~a light incident surface of a photovoltaic cell~~ an electrically conductive or semi-conductive surface having dimensions being defined by peripheral edges of said surface and an electrical interconnect structure, ~~said interconnect structure overlaying and in electrical communication with at least a portion of said surface,~~ said interconnect structure comprising,

- a base substrate and,

- a layered structure, said layered structure comprising layers of a first material and a second material, said layered structure forming a pattern of one or more lines extending over said base substrate,

- ~~a~~ said first material comprising a polymer and characterized as having the ability to assist in deposition of metal, ~~said material comprising a polymer,~~
- said second material comprising a metal deposit covering ~~overlaying at least a portion of~~ said first material,

said combination further characterized as having a first portion of said layered structure extending over said electrically conductive or semi-conductive surface such that said second material is positioned between said first material and said electrically conductive or semi-conductive surface.

42. (Cancelled)

43. (Cancelled)

44. (Currently amended) In combination, an electrically conductive or semi-conductive surface and a current collector structure, said current collector structure comprising one or more ~~electrical~~ traces overlaying a sheetlike substrate, said traces comprising a first material comprising a polymer and having the ability to assist metal deposition, said first material having a first surface and an oppositely facing second surface, said first surface facing said substrate and being devoid of metal coating and said second surface being coated with a metal deposit, said metal in electrical communication with said conductive or semi-conductive surface.

45. (New) The combination of claim 19 wherein said second pattern comprises a monolithic metal deposit substantially in the form of said second pattern.

46. (New) The combination of claim 45 wherein said monolithic metal deposit is an electrodeposit.

47. (New) The combination of claim 19 wherein said first material comprises a polymeric adhesive functioning to adhesively join said electrically conductive material to said first substrate surface.

48. (New) The combination of claim 41 further characterized as having a second portion of said layered pattern extending outside a said peripheral edge of said electrically conductive or semi-conductive surface.

49. (New) The combination of claim 44 wherein said metal deposit comprises an electrodeposit.

50. (New) The combination of claim 44 wherein said first material is in a printed form.